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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce625t-04i-ss

PIC16CE62X

TABLE 1-1: PIC16CE62X FAMILY OF DEVICES

		PIC16CE623	PIC16CE624	PIC16CE625
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	2K
	Data Memory (bytes)	96	96	128
Peripherals	EEPROM Data Memory (bytes)	128	128	128
	Timer Module(s)	TMR0	TMR0	TMR0
	Comparators(s)	2	2	2
	Internal Reference Voltage	Yes	Yes	Yes
Features	Interrupt Sources	4	4	4
	I/O Pins	13	13	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP

All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.
All PIC16CE62X Family devices use serial programming with clock pin RB6 and data pin RB7.

PIC16CE62X

4.2.2.2 OPTION REGISTER

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the external RB0/INT interrupt, TMR0 and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT (PSA = 1).

REGISTER 4-2: OPTION REGISTER (ADDRESS 81H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR reset
-x = Unknown at POR reset

bit 7: **RBPU**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS<2:0>**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

4.2.2.6 PCON REGISTER

The PCON register contains flag bits to differentiate between a Power-on Reset, an external $\overline{\text{MCLR}}$ reset, WDT reset or a Brown-out Reset.

Note: $\overline{\text{BOD}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOD}}$ is cleared, indicating a brown-out has occurred. The $\overline{\text{BOD}}$ status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the configuration word).

REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	POR	$\overline{\text{BOD}}$
bit7						bit0	

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **POR:** Power-on Reset Status bit
 1 = No Power-on Reset occurred
 0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOD}}$:** Brown-out Reset Status bit
 1 = No Brown-out Reset occurred
 0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

R = Readable bit
 W = Writable bit
 U = Unimplemented bit, read as '0'
 -n = Value at POR reset
 -x = Unknown at POR reset

TABLE 5-1: PORTA FUNCTIONS

Name	Bit #	Buffer Type	Function
RA0/AN0	bit0	ST	Input/output or comparator input
RA1/AN1	bit1	ST	Input/output or comparator input
RA2/AN2/VREF	bit2	ST	Input/output or comparator input or VREF output
RA3/AN3	bit3	ST	Input/output or comparator input/output
RA4/T0CKI	bit4	ST	Input/output or external clock input for TMR0 or comparator output. Output is open drain type.

Legend: ST = Schmitt Trigger input

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	---x 0000	---u 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations, read as '0', x = unknown, u = unchanged

Note: Shaded bits are not used by PORTA.

TABLE 5-3: PORTB FUNCTIONS

Name	Bit #	Buffer Type	Function
RB0/INT	bit0	TTL/ST ⁽¹⁾	Input/output or external interrupt input. Internal software programmable weak pull-up.
RB1	bit1	TTL	Input/output pin. Internal software programmable weak pull-up.
RB2	bit2	TTL	Input/output pin. Internal software programmable weak pull-up.
RB3	bit3	TTL	Input/output pin. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock pin.
RB7	bit7	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data pin.

Legend: ST = Schmitt Trigger, TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

Note 2: This buffer is a Schmitt Trigger input when used in serial programming mode.

TABLE 5-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
81h	OPTION	RBP _U	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: u = unchanged, x = unknown

Note: Shaded bits are not used by PORTB.

6.3 Write Operations

6.3.1 BYTE WRITE

Following the start signal from the processor, the device code (4 bits), the don't care bits (3 bits), and the R/W bit, which is a logic low, is placed onto the bus by the processor. This indicates to the EEPROM that a byte with a word address will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the processor is the word address and will be written into the address pointer of the EEPROM. After receiving another acknowledge signal from the EEPROM, the processor will transmit the data word to be written into the addressed memory location. The EEPROM acknowledges again and the processor generates a stop condition. This initiates the internal write cycle, and during this time, the EEPROM will not generate acknowledge signals (Figure 6-5).

6.3.2 PAGE WRITE

The write control byte, word address and the first data byte are transmitted to the EEPROM in the same way as in a byte write. But instead of generating a stop condition, the processor transmits up to eight data bytes to the EEPROM, which are temporarily stored in the on-chip page buffer and will be written into the memory after the processor has transmitted a stop condition. After the receipt of each word, the three lower order address pointer bits are internally incremented by one. The higher order five bits of the word address remains constant. If the processor should transmit more than eight words prior to generating the stop condition, the address counter will roll over and the previously received data will be overwritten. As with the byte write operation, once the stop condition is received, an internal write cycle will begin (Figure 6-6).

6.4 Acknowledge Polling

Since the EEPROM will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the stop condition for a write command has been issued from the processor, the EEPROM initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the processor sending a start condition followed by the control byte for a write command (R/W = 0). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, then the start bit and control byte must be re-sent. If the cycle is complete, then the device will return the ACK and the processor can then proceed with the next read or write command. See Figure 6-4 for flow diagram.

FIGURE 6-4: ACKNOWLEDGE POLLING FLOW

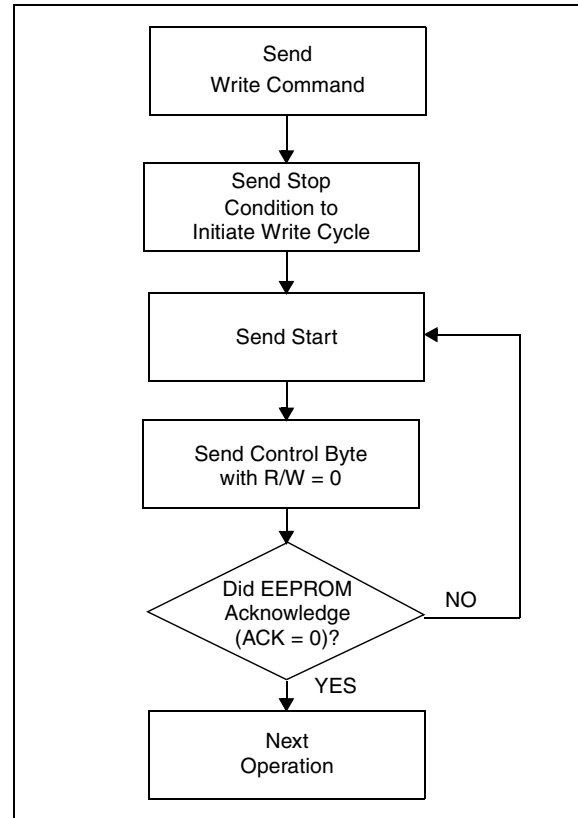
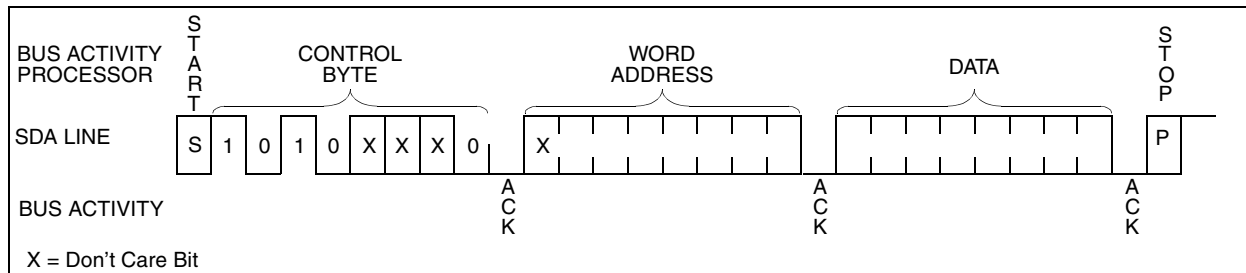


FIGURE 6-5: BYTE WRITE



8.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note: If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of CMCON. This will end the mismatch condition.
- b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

8.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will

wake-up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

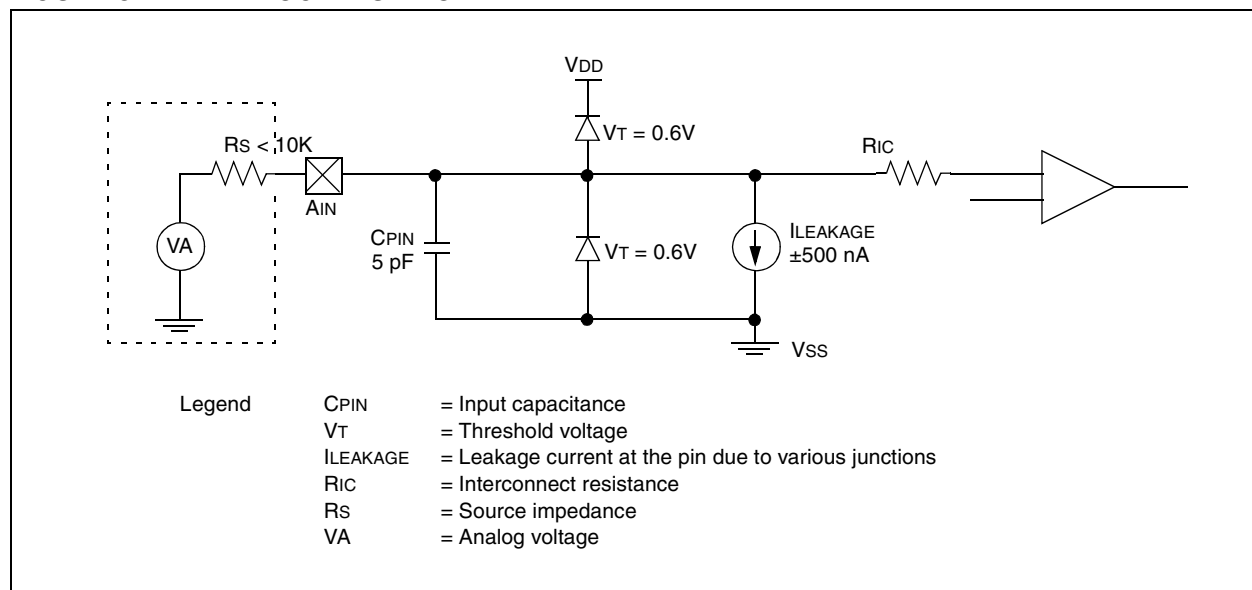
8.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

8.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 8-4: ANALOG INPUT MODEL



9.0 VOLTAGE REFERENCE MODULE

The Voltage Reference is a 16-tap resistor ladder network that provides a selectable voltage reference. The resistor ladder is segmented to provide two ranges of VREF values and has a power-down function to conserve power when the reference is not being used. The VRCON register controls the operation of the reference as shown in Register 9-1. The block diagram is given in Figure 9-1.

9.1 Configuring the Voltage Reference

The Voltage Reference can output 16 distinct voltage levels for each range.

The equations used to calculate the output of the Voltage Reference are as follows:

$$\text{if } VRR = 1: VREF = (VR<3:0>/24) \times VDD$$

$$\text{if } VRR = 0: VREF = (VDD \times 1/4) + (VR<3:0>/32) \times VDD$$

The setting time of the Voltage Reference must be considered when changing the VREF output (Table 13-1). Example 9-1 shows an example of how to configure the Voltage Reference for an output voltage of 1.25V with VDD = 5.0V.

REGISTER 9-1: VRCON REGISTER (ADDRESS 9Fh)

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	VROE	VRR	—	VR3	VR2	VR1	VR0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **VREN:** VREF Enable
1 = VREF circuit powered on
0 = VREF circuit powered down, no IDD drain

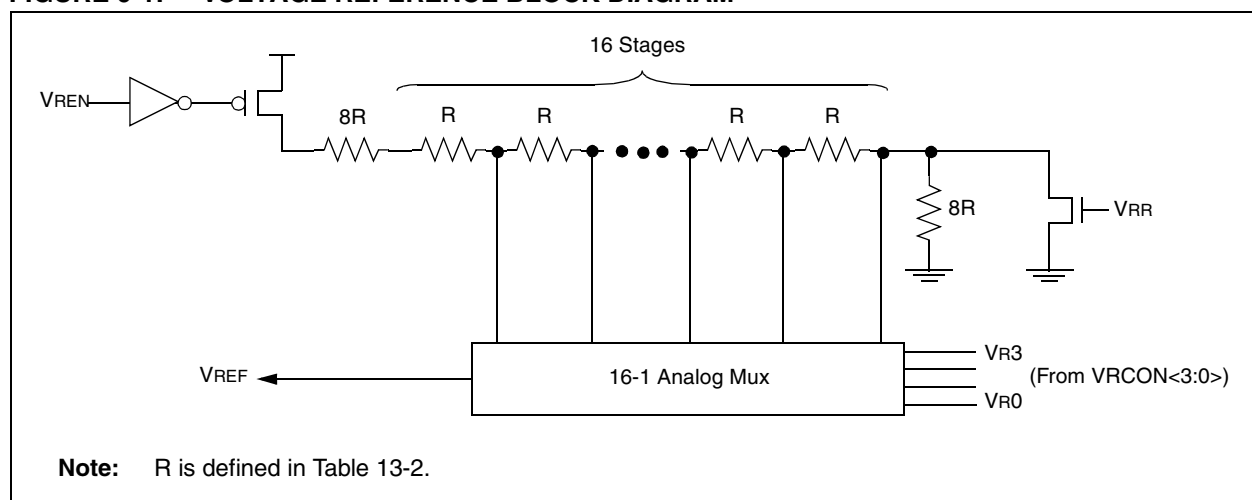
bit 6: **VROE:** VREF Output Enable
1 = VREF is output on RA2 pin
0 = VREF is disconnected from RA2 pin

bit 5: **VRR:** VREF Range selection
1 = Low Range
0 = High Range

bit 4: **Unimplemented:** Read as '0'

bit 3-0: **VR<3:0>:** VREF value selection $0 \leq VR[3:0] \leq 15$
when VRR = 1: $VREF = (VR<3:0>/24) \times VDD$
when VRR = 0: $VREF = 1/4 \times VDD + (VR<3:0>/32) \times VDD$

FIGURE 9-1: VOLTAGE REFERENCE BLOCK DIAGRAM



EXAMPLE 9-1: VOLTAGE REFERENCE CONFIGURATION

```

MOVLW    0x02        ; 4 Inputs Muxed
MOVWF    CMCON        ; to 2 comps.
BSF      STATUS,RP0   ; go to Bank 1
MOVLW    0x07        ; RA3-RA0 are
MOVWF    TRISA        ; outputs
MOVLW    0xA6        ; enable VREF
MOVWF    VRCON        ; low range
                        ; set VR<3:0>=6

BCF      STATUS,RP0   ; go to Bank 0
CALL     DELAY10      ; 10µs delay
    
```

9.2 Voltage Reference Accuracy/Error

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 9-1) keep VREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the VREF output changes with fluctuations in VDD. The absolute accuracy of the Voltage Reference can be found in Table 13-2.

9.3 Operation During Sleep

When the device wakes up from sleep through an interrupt or a Watchdog Timer time-out, the contents of the VRCON register are not affected. To minimize current consumption in SLEEP mode, the Voltage Reference should be disabled.

9.4 Effects of a Reset

A device reset disables the Voltage Reference by clearing bit VREN (VRCON<7>). This reset also disconnects the reference from the RA2 pin by clearing bit VROE (VRCON<6>) and selects the high voltage range by clearing bit VRR (VRCON<5>). The VREF value select bits, VRCON<3:0>, are also cleared.

9.5 Connection Considerations

The Voltage Reference Module operates independently of the comparator module. The output of the reference generator may be connected to the RA2 pin if the TRISA<2> bit is set and the VROE bit, VRCON<6>, is set. Enabling the Voltage Reference output onto the RA2 pin with an input signal present will increase current consumption. Connecting RA2 as a digital output with VREF enabled will also increase current consumption.

The RA2 pin can be used as a simple D/A output with limited drive capability. Due to the limited drive capability, a buffer must be used in conjunction with the Voltage Reference output for external connections to VREF. Figure 9-2 shows an example buffering technique.

FIGURE 9-2: VOLTAGE REFERENCE OUTPUT BUFFER EXAMPLE

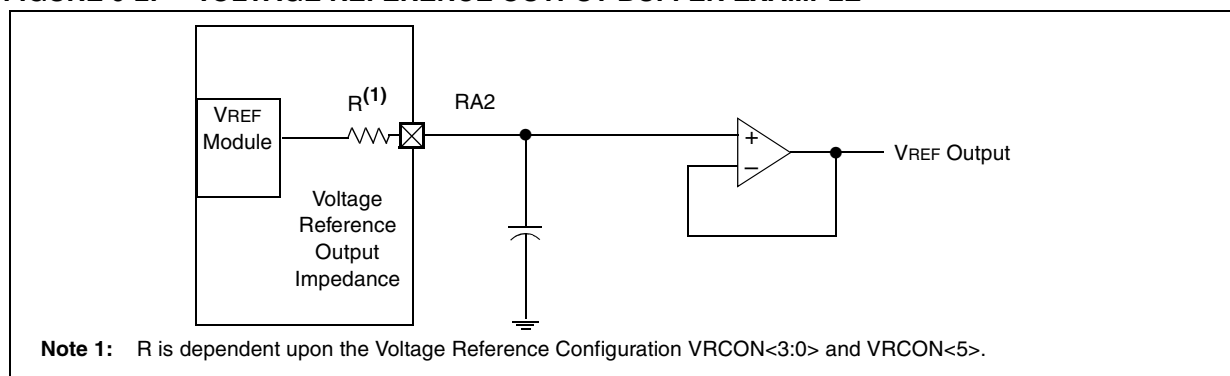


TABLE 9-1: REGISTERS ASSOCIATED WITH VOLTAGE REFERENCE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value On POR / BOD	Value On All Other Resets
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: - = Unimplemented, read as "0"

PIC16CE62X

10.1 Configuration Bits

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h – 3FFFh), which can be accessed only during programming.

REGISTER 10-1: CONFIGURATION WORD

CP1	CP0 ⁽²⁾	CP1	CP0 ⁽²⁾	CP1	CP0 ⁽²⁾	—	BODEN ⁽¹⁾	CP1	CP0 ⁽²⁾	PWRT ⁽¹⁾	WDTE	FOSC1	FOSC0	CONFIG Address REGISTER: 2007h
bit13													bit0	
bit 13-8: CP1:CP0 Pairs: Code protection bit pairs ⁽²⁾														
5-4: Code protection for 2K program memory														
11 = Program memory code protection off														
10 = 0400h-07FFh code protected														
01 = 0200h-07FFh code protected														
00 = 0000h-07FFh code protected														
Code protection for 1K program memory														
11 = Program memory code protection off														
10 = Program memory code protection on														
01 = 0200h-03FFh code protected														
00 = 0000h-03FFh code protected														
Code protection for 0.5K program memory														
11 = Program memory code protection off														
10 = Program memory code protection off														
01 = Program memory code protection off														
00 = 0000h-01FFh code protected														
bit 7: Unimplemented: Read as '1'														
bit 6: BODEN: Brown-out Reset Enable bit ⁽¹⁾														
1 = BOD enabled														
0 = BOD disabled														
bit 3: PWRT: Power-up Timer Enable bit ⁽¹⁾														
1 = PWRT disabled														
0 = PWRT enabled														
bit 2: WDTE: Watchdog Timer Enable bit														
1 = WDT enabled														
0 = WDT disabled														
bit 1-0: FOSC1:FOSC0: Oscillator Selection bits														
11 = RC oscillator														
10 = HS oscillator														
01 = XT oscillator														
00 = LP oscillator														
Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT), regardless of the value of bit <u>PWRT</u> . Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.														
2: All of the CP<1:0> pairs have to be given the same value to enable the code protection scheme listed.														

10.3 Reset

The PIC16CE62X differentiates between various kinds of reset:

- Power-on reset (POR)
- $\overline{\text{MCLR}}$ reset during normal operation
- $\overline{\text{MCLR}}$ reset during SLEEP
- WDT reset (normal operation)
- WDT wake-up (SLEEP)
- Brown-out Reset (BOD)

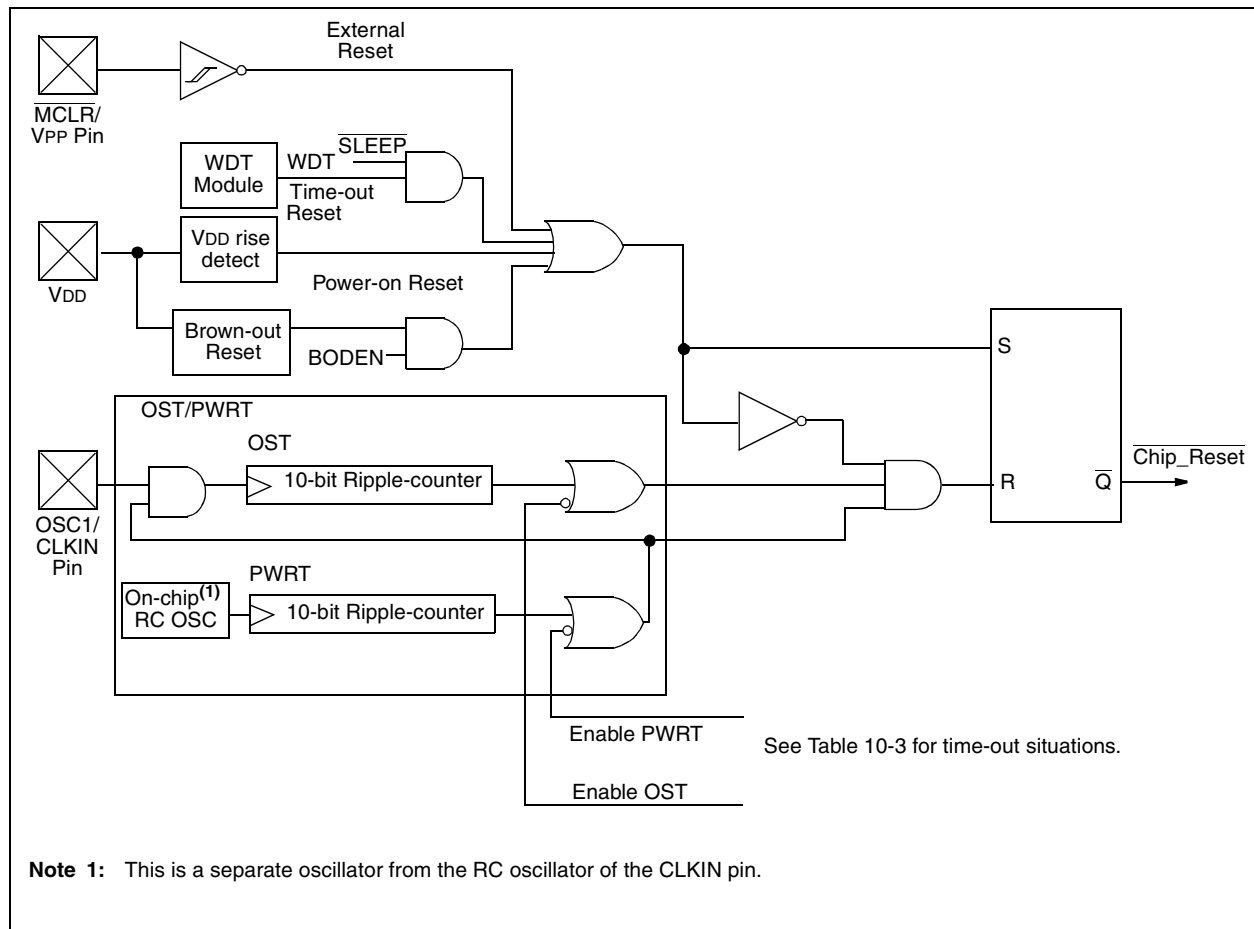
Some registers are not affected in any reset condition. Their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a “reset

state” on Power-on reset, $\overline{\text{MCLR}}$ reset, WDT reset and $\overline{\text{MCLR}}$ reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different reset situations as indicated in Table 10-4. These bits are used in software to determine the nature of the reset. See Table 10-6 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 10-6.

The $\overline{\text{MCLR}}$ reset path has a noise filter to detect and ignore small pulses. See Table 13-5 for pulse width specification.

FIGURE 10-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



10.4.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired, then OST is activated. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRT}}\text{E}$ bit status. For example, in RC mode with $\overline{\text{PWRT}}\text{E}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 10-8, Figure 10-9 and Figure 10-10 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 10-9). This is useful for testing purposes or to synchronize more than one PIC® device operating in parallel.

Table 10-5 shows the reset conditions for some special registers, while Table 10-6 shows the reset conditions for all the registers.

10.4.6 POWER CONTROL (PCON)/STATUS REGISTER

The power control/status register, PCON (address 8Eh) has two bits.

Bit0 is $\overline{\text{BOR}}$ (Brown-out). $\overline{\text{BOR}}$ is unknown on power-on-reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}} = 0$ indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BODEN bit = 0 in the Configuration word).

Bit1 is $\overline{\text{POR}}$ (Power-on-reset). It is a '0' on power-on-reset and unaffected otherwise. The user must write a '1' to this bit following a power-on-reset. On a subsequent reset, if $\overline{\text{POR}}$ is '0', it will indicate that a power-on-reset must have occurred (VDD may have gone too low).

TABLE 10-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset	Wake-up from SLEEP
	$\overline{\text{PWRT}}\text{E} = 0$	$\overline{\text{PWRT}}\text{E} = 1$		
XT, HS, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms + 1024 TOSC	1024 TOSC
RC	72 ms	—	72 ms	—

TABLE 10-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	X	1	1	Power-on-reset
0	X	0	X	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	X	X	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	X	X	Brown-out Reset
1	1	0	u	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{\text{MCLR}}$ reset during normal operation
1	1	1	0	$\overline{\text{MCLR}}$ reset during SLEEP

Legend: x = unknown, u = unchanged

11.0 INSTRUCTION SET SUMMARY

Each PIC16CE62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CE62X instruction set summary in Table 11-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 11-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 11-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
w	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
()	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
<i>italics</i>	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 11-1 lists the instructions recognized by the MPASM assembler.

Figure 11-1 shows the three general formats that the instructions can have.

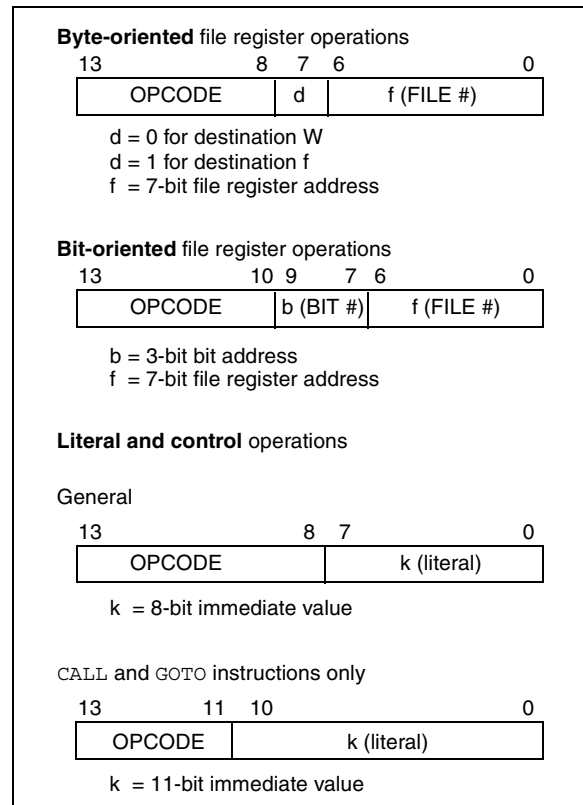
Note: To maintain upward compatibility with future PIC® MCU products, do not use the `OPTION` and `TRIS` instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 11-1: GENERAL FORMAT FOR INSTRUCTIONS



13.2 DC CHARACTERISTICS: PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature				
			$-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	—	—	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)*
			—	—	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT osc mode, (Note 4)
			—	35	70	μA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	—	—	2.0	μA	VDD = 2.5V
			—	—	2.2	μA	VDD = 3.0V*
			—	—	9.0	μA	VDD = 5.5V
			—	—	15	μA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current (Note 5)	—	6.0	10	μA	VDD=4.0V
D022A	ΔIBOR	Brown-out Reset Current (Note 5)	—	75	125	μA	(125°C) BOD enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator (Note 5)	—	30	60	μA	VDD = 4.0V
D023A	ΔIVREF	VREF Current (Note 5)	—	80	135	μA	VDD = 4.0V
	ΔIEE Write	Operating Current	—	—	3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	—	—	1	mA	
	ΔIEE	Standby Current	—	—	30	μA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	—	—	100	μA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = V_{DD}/2R_{ext}$ (mA) with Rext in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

PIC16CE62X

13.3 DC CHARACTERISTICS:

PIC16CE62X-04 (Commercial, Industrial, Extended)
PIC16CE62X-20 (Commercial, Industrial, Extended)
PIC16LCE62X (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq \text{TA} \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq \text{TA} \leq +125^{\circ}\text{C}$ for extended				
			Operating voltage VDD range as described in DC spec Table 13-1				
Parm No.	Sym	Characteristic	Min	Typ†	Max	Unit	Conditions
D030	VIL	Input Low Voltage I/O ports with TTL buffer	VSS	–	0.8V 0.15VDD	V	VDD = 4.5V to 5.5V, Otherwise
D031		with Schmitt Trigger input	VSS		0.2VDD	V	
D032		MCLR, RA4/T0CKI, OSC1 (in RC mode)	VSS	–	0.2VDD	V	Note1
D033		OSC1 (in XT and HS)	VSS	–	0.3VDD	V	
		OSC1 (in LP)	VSS	–	0.6VDD - 1.0	V	
D040	VIH	Input High Voltage I/O ports with TTL buffer	2.0V .25VDD + 0.8V	–	VDD VDD	V	VDD = 4.5V to 5.5V, Otherwise
D041		with Schmitt Trigger input	0.8VDD		VDD	V	
D042		MCLR RA4/T0CKI	0.8VDD	–	VDD	V	
D043		OSC1 (XT, HS and LP)	0.7VDD	–	VDD	V	
D043A		OSC1 (in RC mode)	0.9VDD				Note1
D070	IPURB	PORTB weak pull-up current	50	200	400	μA	VDD = 5.0V, VPIN = VSS
D060	IIL	Input Leakage Current (Notes 2, 3) I/O ports (Except PORTA)	–	–	±1.0	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D061		PORTA	–	–	±0.5	μA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D063		RA4/T0CKI	–	–	±1.0	μA	VSS ≤ VPIN ≤ VDD
		OSC1, MCLR	–	–	±5.0	μA	VSS ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
D080	VOL	Output Low Voltage I/O ports	–	–	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to $+85^{\circ}\text{C}$
			–	–	0.6	V	IOL=7.0 mA, VDD=4.5V, $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC only)	–	–	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to $+85^{\circ}\text{C}$
			–	–	0.6	V	IOL=1.2 mA, VDD=4.5V, $+125^{\circ}\text{C}$
D090	VOH	Output High Voltage (Note 3) I/O ports (Except RA4)	VDD-0.7	–	–	V	IOH=-3.0 mA, VDD=4.5V, -40° to $+85^{\circ}\text{C}$
			VDD-0.7	–	–	V	IOH=-2.5 mA, VDD=4.5V, $+125^{\circ}\text{C}$
D092		OSC2/CLKOUT (RC only)	VDD-0.7	–	–	V	IOH=-1.3 mA, VDD=4.5V, -40° to $+85^{\circ}\text{C}$
			VDD-0.7	–	–	V	IOH=-1.0 mA, VDD=4.5V, $+125^{\circ}\text{C}$
*D150	VOD	Open-Drain High Voltage			8.5	V	RA4 pin
D100	COSC2	Capacitive Loading Specs on Output Pins OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101	Cio	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16CE62X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

13.5 Timing Diagrams and Specifications

FIGURE 13-5: EXTERNAL CLOCK TIMING

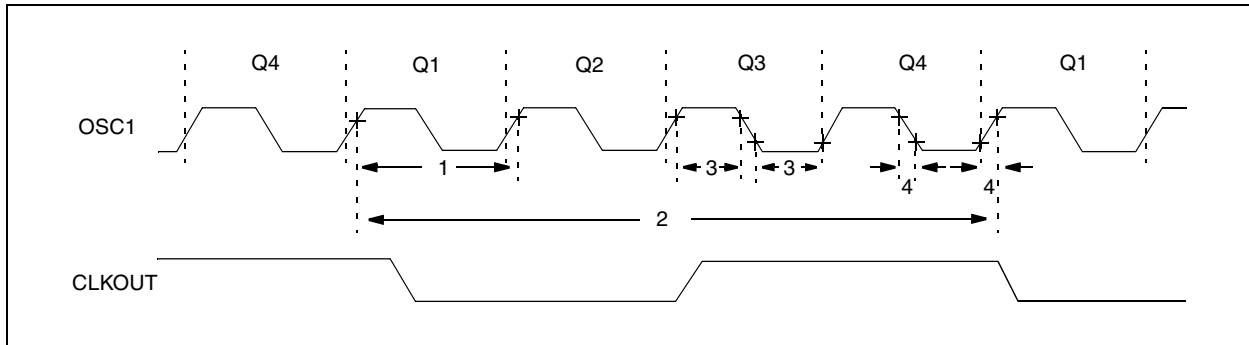


TABLE 13-3: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT and RC osc mode, VDD=5.0V
			DC	—	20	MHz	HS osc mode
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode, VDD=5.0V
			0.1	—	4	MHz	XT osc mode
			1	—	20	MHz	HS osc mode
			DC	—	200	kHz	LP osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT and RC osc mode
			50	—	—	ns	HS osc mode
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			50	—	1,000	ns	HS osc mode
			5	—	—	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	200	—	DC	ns	Tcy=Fosc/4
3*	TosL, TosH	External Clock in (OSC1) High or Low Time	100*	—	—	ns	XT oscillator, TosC L/H duty cycle
			2*	—	—	μs	LP oscillator, TosC L/H duty cycle
			20*	—	—	ns	HS oscillator, TosC L/H duty cycle
4*	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	25*	—	—	ns	XT oscillator
			50*	—	—	ns	LP oscillator
			15*	—	—	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

13.6 EEPROM Timing

FIGURE 13-10: BUS TIMING DATA

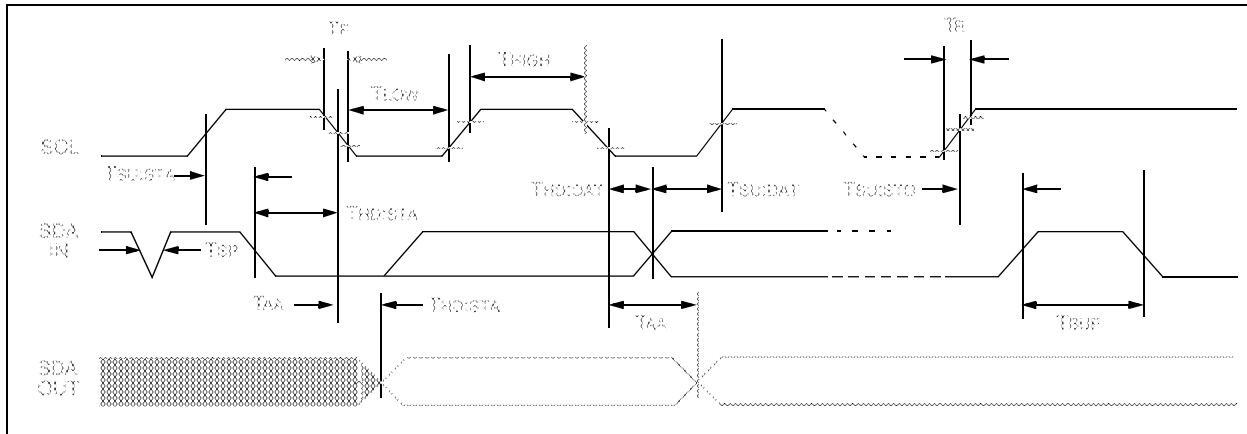


TABLE 13-7: AC CHARACTERISTICS

Parameter	Symbol	STANDARD MODE		Vcc = 4.5 - 5.5V FAST MODE		Units	Remarks
		Min.	Max.	Min.	Max.		
Clock frequency	FCLK	—	100	—	400	kHz	
Clock high time	THIGH	4000	—	600	—	ns	
Clock low time	TLOW	4700	—	1300	—	ns	
SDA and SCL rise time	TR	—	1000	—	300	ns	(Note 1)
SDA and SCL fall time	TF	—	300	—	300	ns	(Note 1)
START condition hold time	THD:STA	4000	—	600	—	ns	After this period the first clock pulse is generated
START condition setup time	TSU:STA	4700	—	600	—	ns	Only relevant for repeated START condition
Data input hold time	THD:DAT	0	—	0	—	ns	(Note 2)
Data input setup time	TSU:DAT	250	—	100	—	ns	
STOP condition setup time	TSU:STO	4000	—	600	—	ns	
Output valid from clock	TAA	—	3500	—	900	ns	(Note 2)
Bus free time	TBUF	4700	—	1300	—	ns	Time the bus must be free before a new transmission can start
Output fall time from VIH minimum to VIL maximum	TOF	—	250	20 + 0.1 CB	250	ns	(Note 1), CB ≤ 100 pF
Input filter spike suppression (SDA and SCL pins)	TSP	—	50	—	50	ns	(Note 3)
Write cycle time	TWR	—	10	—	10	ms	Byte or Page mode
Endurance	—	10M 1M	—	10M 1M	—	cycles	25°C, Vcc = 5.0V, Block Mode (Note 4)

Note 1: Not 100% tested. CB = total capacitance of one bus line in pF.

Note 2: As a transmitter, the device must provide an internal minimum delay time to bridge the undefined region (minimum 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

Note 3: The combined TSP and VHYS specifications are due to new Schmitt trigger inputs which provide improved noise spike suppression. This eliminates the need for a TI specification for standard operation.

Note 4: This parameter is not tested but guaranteed by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which can be obtained on our website.

PIC16CE62X

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PIC16CE62X PRODUCT IDENTIFICATION SYSTEM

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.

PART NO.	-XX	X	/XX	XXX	
					Pattern: 3-Digit Pattern Code for QTP (blank otherwise)
					Package: P = PDIP SO = SOIC (Gull Wing, 300 mil body) SS = SSOP (209 mil) JW* = Windowed CERDIP
					Temperature Range: - = 0°C to +70°C I = -40°C to +85°C E = -40°C to +125°C
					Frequency Range: 04 = 200kHz (LP osc) 04 = 4 MHz (XT and RC osc) 20 = 20 MHz (HS osc)
					Device: PIC16CE62X :VDD range 3.0V to 5.5V PIC16CE62XT:VDD range 3.0V to 5.5V (Tape and Reel)

Examples:
a) PIC16CE623-04/P301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.
b) PIC16CE623-04I/SO = Industrial temp., SOIC package, 4MHz, industrial VDD limits.

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)